

Emeka H Amalu

List of Publications by Year in descending order

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18
papers

608
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536
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Effective Solder for Improved Thermo-Mechanical Reliability of Solder Joints in a Ball Grid Array (BGA) Soldered on Printed Circuit Board (PCB). <i>Journal of Electronic Materials</i> , 2021, 50, 263-282. | 1.0 | 29 |
| 2 | A review of technology, materials and R&D challenges of upper limb prosthesis for improved user suitability. <i>Journal of Orthopaedics</i> , 2021, 23, 88-96. | 0.6 | 17 |
| 3 | Thermal fatigue life of ball grid array (BGA) solder joints made from different alloy compositions. <i>Engineering Failure Analysis</i> , 2021, 125, 105447. | 1.8 | 49 |
| 4 | Comparing and Benchmarking Fatigue Behaviours of Various SAC Solders under Thermo-Mechanical Loading. , 2020, , . | | 3 |
| 5 | Creep Damage of BGA Solder Interconnects Subjected to Thermal Cycling and Isothermal Ageing. , 2019, , . | | 5 |
| 6 | Effect of Relative Density on Compressive Load Response of Crumpled Aluminium Foil Mesh. <i>Materials</i> , 2019, 12, 4018. | 1.3 | 4 |
| 7 | Effect of operating temperature on degradation of solder joints in crystalline silicon photovoltaic modules for improved reliability in hot climates. <i>Solar Energy</i> , 2018, 170, 682-693. | 2.9 | 63 |
| 8 | Evaluation of thermo-mechanical damage and fatigue life of solar cell solder interconnections. <i>Robotics and Computer-Integrated Manufacturing</i> , 2017, 47, 37-43. | 6.1 | 49 |
| 9 | A review of photovoltaic module technologies for increased performance in tropical climate. <i>Renewable and Sustainable Energy Reviews</i> , 2017, 75, 1225-1238. | 8.2 | 80 |
| 10 | Modelling evaluation of Garofalo-Arrhenius creep relation for lead-free solder joints in surface mount electronic component assemblies. <i>Journal of Manufacturing Systems</i> , 2016, 39, 9-23. | 7.6 | 47 |
| 11 | A review of interconnection technologies for improved crystalline silicon solar cell photovoltaic module assembly. <i>Applied Energy</i> , 2015, 154, 173-182. | 5.1 | 115 |
| 12 | Effect of component standoff height on thermo-mechanical reliability of ball grid array (BGA) solder joints operating in high-temperature ambient. , 2015, , . | | 4 |
| 13 | Optimisation of thermo-fatigue reliability of solder joints in surface mount resistor assembly using Taguchi method. <i>Finite Elements in Analysis and Design</i> , 2015, 107, 13-27. | 1.7 | 19 |
| 14 | High-temperature fatigue life of flip chip lead-free solder joints at varying component stand-off height. <i>Microelectronics Reliability</i> , 2012, 52, 2982-2994. | 0.9 | 12 |
| 15 | Damage of lead-free solder joints in flip chip assemblies subjected to high-temperature thermal cycling. <i>Computational Materials Science</i> , 2012, 65, 470-484. | 1.4 | 22 |
| 16 | Prediction of damage and fatigue life of high-temperature flip chip assembly interconnections at operations. <i>Microelectronics Reliability</i> , 2012, 52, 2731-2743. | 0.9 | 14 |
| 17 | High temperature reliability of lead-free solder joints in a flip chip assembly. <i>Journal of Materials Processing Technology</i> , 2012, 212, 471-483. | 3.1 | 60 |
| 18 | Investigation of effects of heat sinks on thermal performance of microelectronic package. , 2011, , . | | 16 |